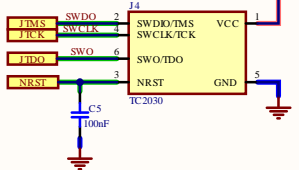
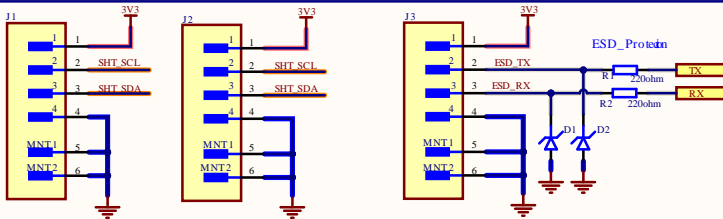


## Temperature\_Humidity\_BLE\_SensorNode

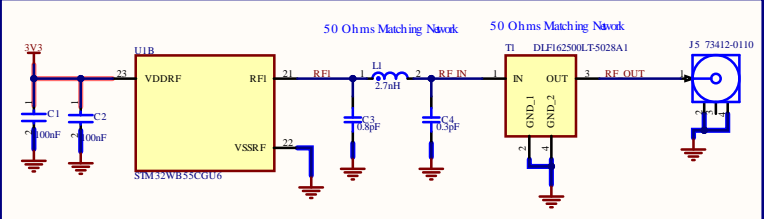
TAG\_Connector\_SWD



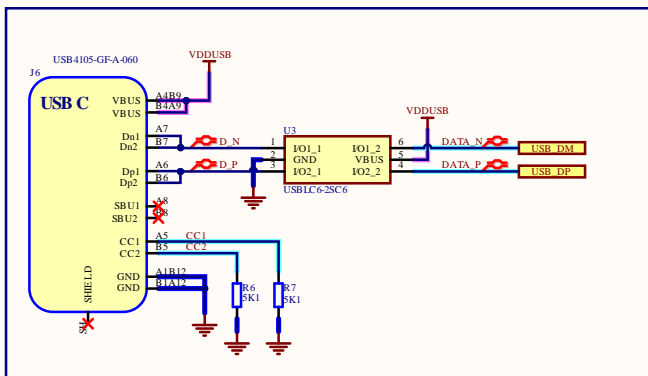
JST\_PH\_Connector\_UART



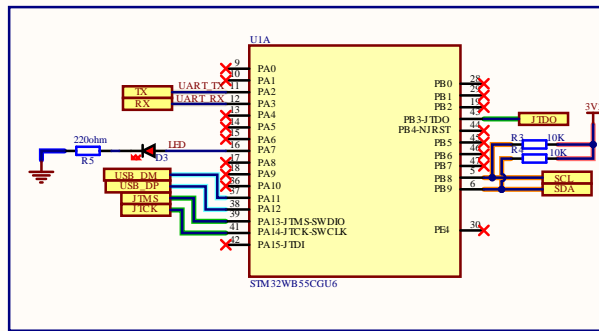
Impedance\_Matching\_BLE\_Antenna



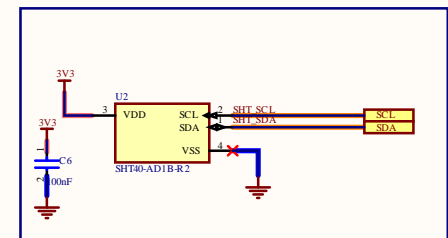
USB\_Type\_C\_Interface



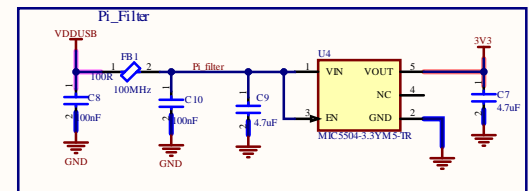
## Input\_Output\_peripherals\_Interface



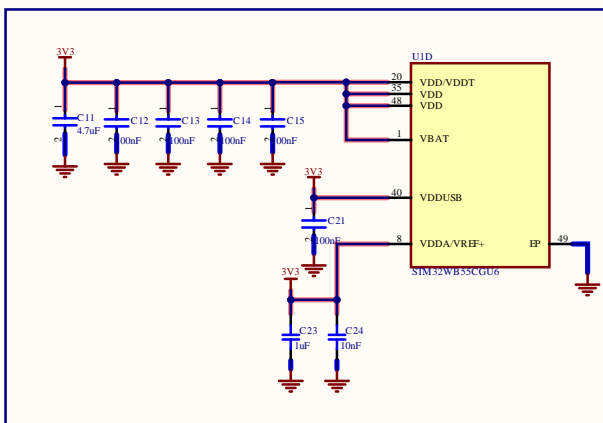
Temperature\_Humidity\_Sensor



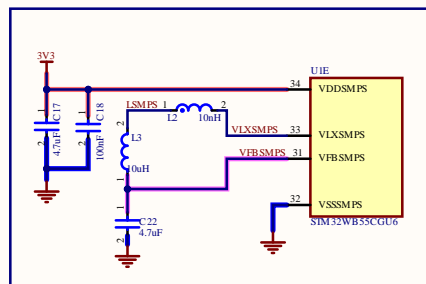
### 3V3\_Fixed\_Low\_Dropout\_Regulator



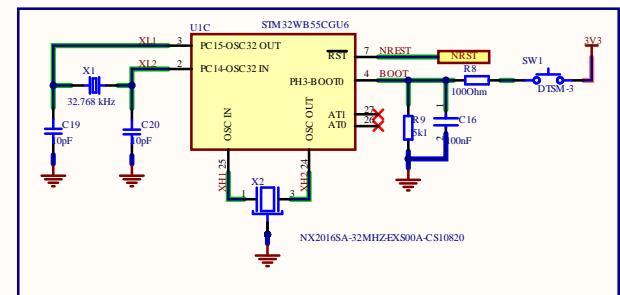
Filter\_External\_Power\_Source



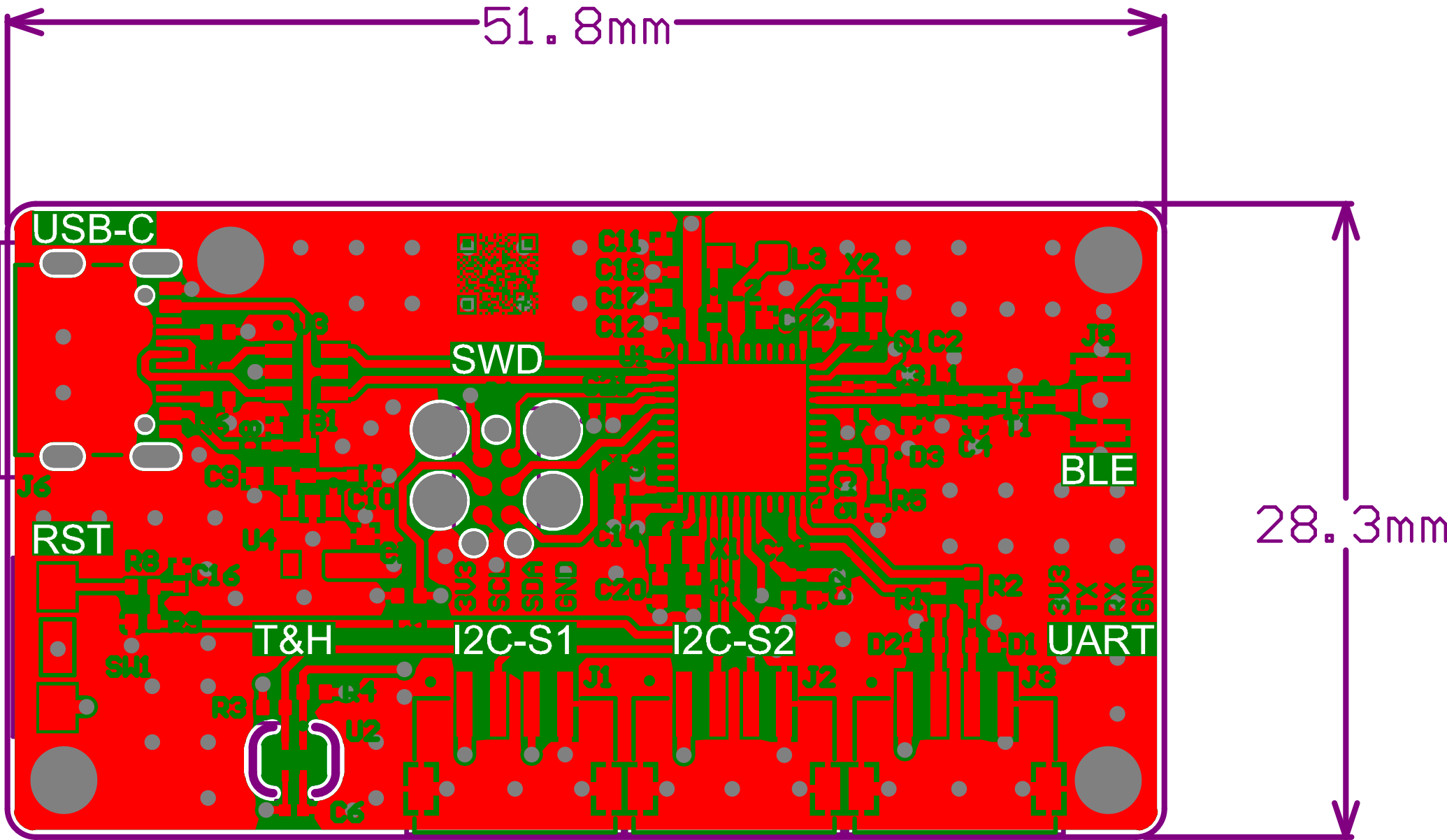
### Filters\_Internal\_SMPS\_Circuit

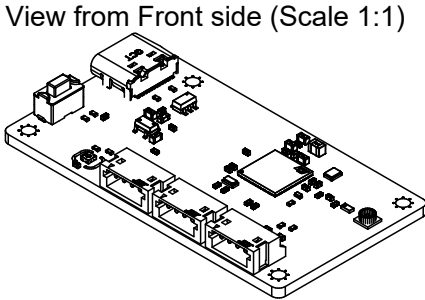
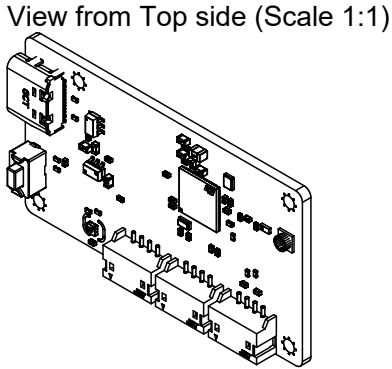
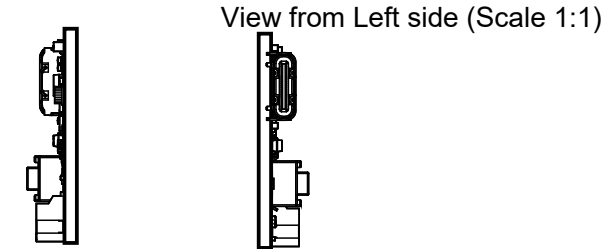
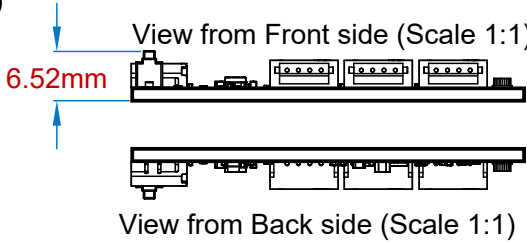
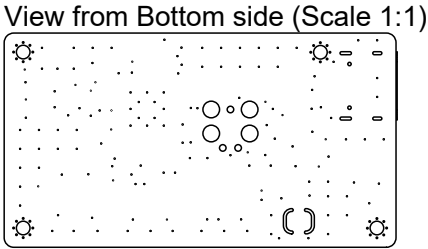
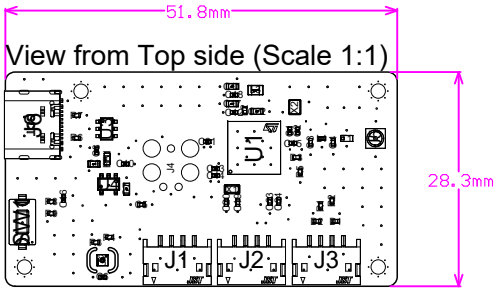


External\_Crystal\_Circuit

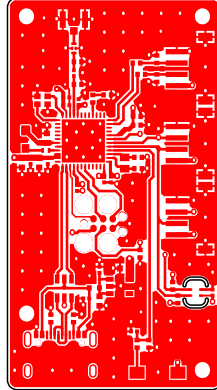


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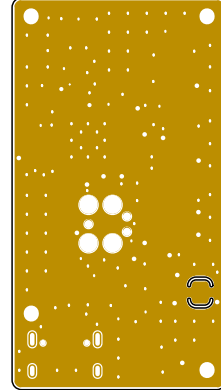




L1 (Scale 1:1)



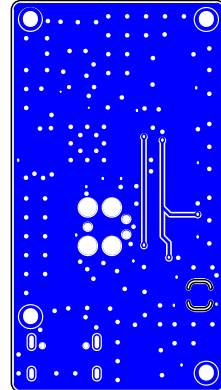
L2 (Scale 1:1)



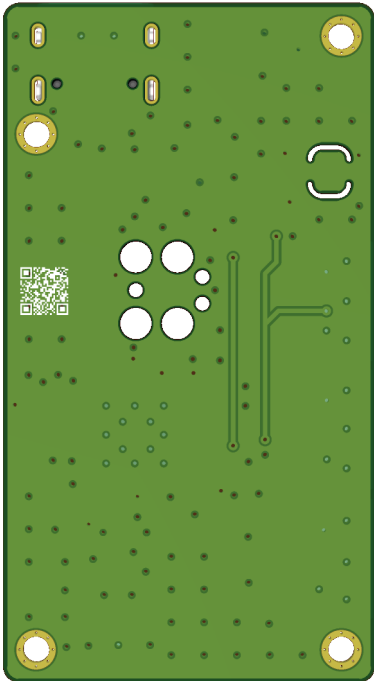
L3 (Scale 1:1)



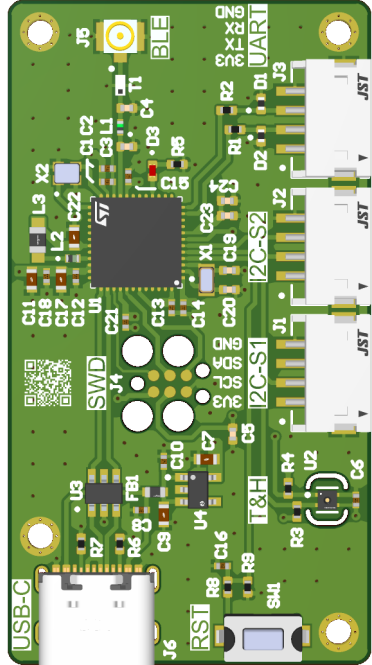
L4 (Scale 1:1)



Realistic Bottom View



Realistic Top View



Layer Stack Legend

Material	Layer	Thickness	Dielectric Material	Type
	Top Overlay			Legend
Surface Material	Top Solder	0.03mm	Solder Resist	Solder Mask
Copper	L1	0.04mm		Signal
Prepreg		0.21mm	PP-022	Dielectric
CF-004	L2	0.02mm		Signal
Prepreg		1.06mm	FR-4	Dielectric
CF-004	L3	0.02mm		Signal
Prepreg		0.21mm	PP-022	Dielectric
Copper	L4	0.04mm		Signal
Surface Material	Bottom Solder	0.03mm	Solder Resist	Solder Mask
	Bottom Overlay			Legend

Total thickness: 1.64mm